

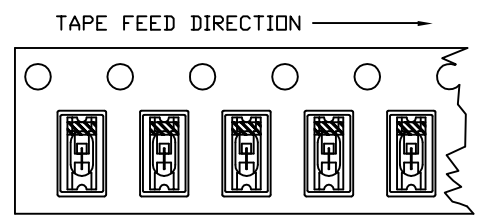
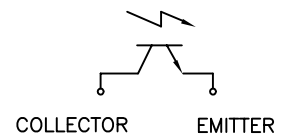
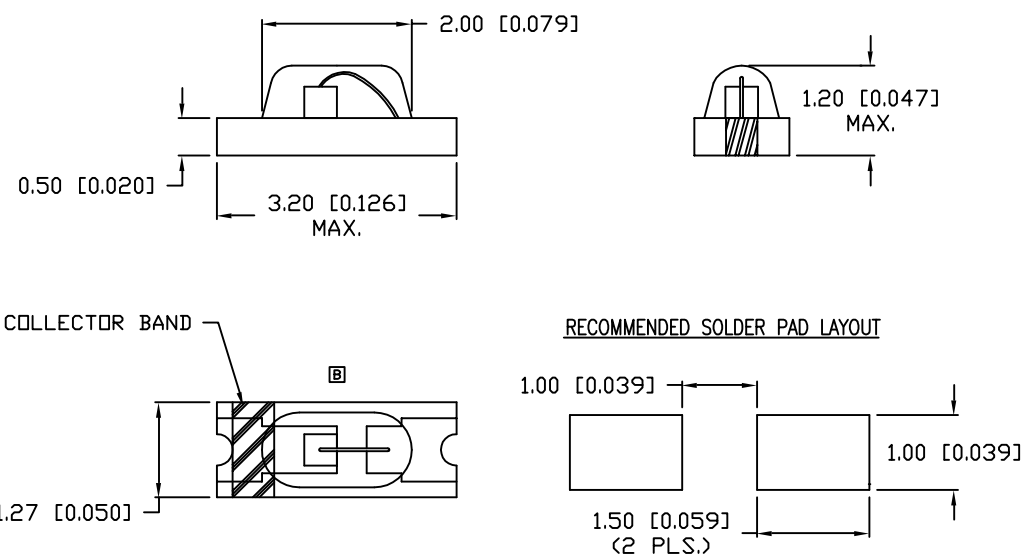
PART NUMBER		REV.
OED-ST-44F		D
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	1.5.95
B	E.C.N. #10434.	6.3.98
C	E.C.N. #10936. & #10BRDR	12.11.02
D	E.C.N. #E11062	12.3.03

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
COLLECTOR DARK CURRENT			400	nA	$V_{ce} = 10\text{V}$ $E_e = 0 \text{ mw/cm}^2$
COLLECTOR LIGHT CURRENT		3.0		mA	$V_{ce} = 5\text{V}$ $E_v=1000\text{LUX}$
COLLECTOR-EMITTER SATURATION VOLTAGE			0.3	V	$I_c=1\text{mA}$ $E_v=1000\text{LUX}$
SWITCHING SPEEDS:					$V_{ce}=5\text{V}$
	RISING TIME		10	$\mu\text{S}$	$I_c=1\text{mA}$
FALLING TIME		10		$\mu\text{S}$	$R_I = 1000 \Omega$
PEAK WAVELENGTH SENSITIVITY		850		nm	
LENS COLOR: WATER CLEAR					

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
COLLECTOR-EMITTER VOLTAGE ( $V_{ce0}$ )	70	V
EMITTER-COLLECTOR VOLTAGE ( $V_{ce0}$ )	5	mA
COLLECTOR CURRENT	100	mA
POWER DISSIPATION	200	mW
OPERATING TEMP.	-25 TO +85	°C
STORAGE TEMP.	-25 TO +120	°C



\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN=  $\begin{matrix} +\text{DECIMAL PRECISION} \\ -0.00 \end{matrix}$  MAX=  $\begin{matrix} +0.00 \\ -\text{DECIMAL PRECISION} \end{matrix}$

REV.	PART NUMBER
D	OED-ST-44F

**CONFIDENTIAL INFORMATION**  
THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.



290 E. HELEN ROAD  
PALATINE, IL 60067-6976  
PHONE: +1.847.359.2790  
US WEB: www.lumex.com  
TW WEB: www.lumex.com.tw

CERAMIC CHIP, SURFACE MOUNT PHOTOTRANSISTOR,  
WATER CLEAR LENS, TAPE AND REEL.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
CT			12.11.02
			PAGE: 1 OF 1
			SCALE: N/A